

LLNL TPCs

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February 5, 2014

Long History of TPCs at LLNL

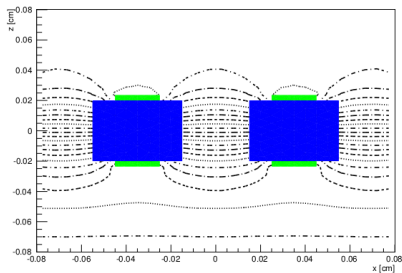
- ▶ **E910/E895** AGS, Au+Au and p+Au collisions EOS-TPC
- ▶ **E907 (aka MIPP)** FNAL Booster, p+Au collisions EOS-TPC
- ▶ **nTPC** neutron TPC, locate sources of neutrons, custom built
- ▶ **fissionTPC** Make high-accuracy cross section measurements of actinides, custom built
- ▶ **nEXO** Just starting, next generation
- ▶ **neg Ion TPC** Reach the intrinsic energy resolution limit, development TPC
- ▶ **LUX** Dark matter, dual phase. Collaboration member and some subsystems
- ▶ **Cohearant ν scatter** Measure this unseen reaction, development TPC
- ▶ **Others...(pre-history)**, STAR TPC, FTPC, EOS-TPC, xenon Compton camera, ...

Workforce

- ▶ Many of the physicists that worked on these projects are still at LLNL
- ▶ We have many engineers
 - ▶ Mechanical (e.g. Phenix Magnet: Bob Yamamoto, Joel Bowers)
 - ▶ Electrical (e.g. fissionTPC electronics: Vincent Riot)
 - ▶ Project Management
 - ▶ Many subfield special engineering labs and expertise
- ▶ Techs
 - ▶ Mechanical Drawing/Design
 - ▶ Machine shops
 - ▶ PCB layout
 - ▶ Electronics assembly (0201's common. 0.4 mm pitch connectors common.)
- ▶ Experience with what is better done in industry, PCB fab/loading, simple machining, etc...

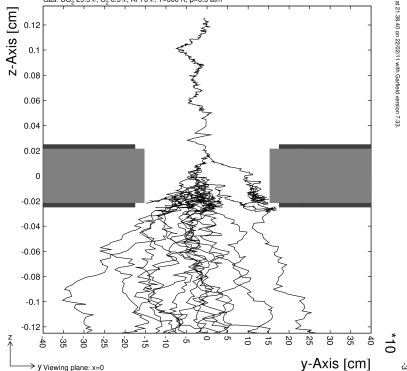
Examples of Relevant LLNL TPC Hardware Field Simulations

Elmer and Garfield Simulations of a LEM



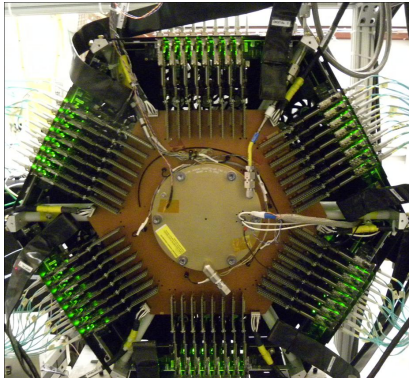
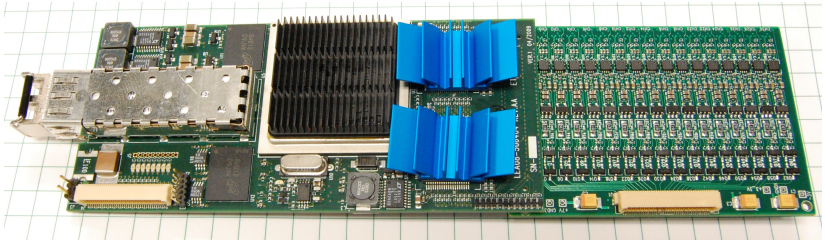
38-Electron Avalanche, LEM Voltage = 740 V

Gas: CO₂ 29.5%, O₂ 0.5%, Ar 70%, T=300 K, p=0.5 atm



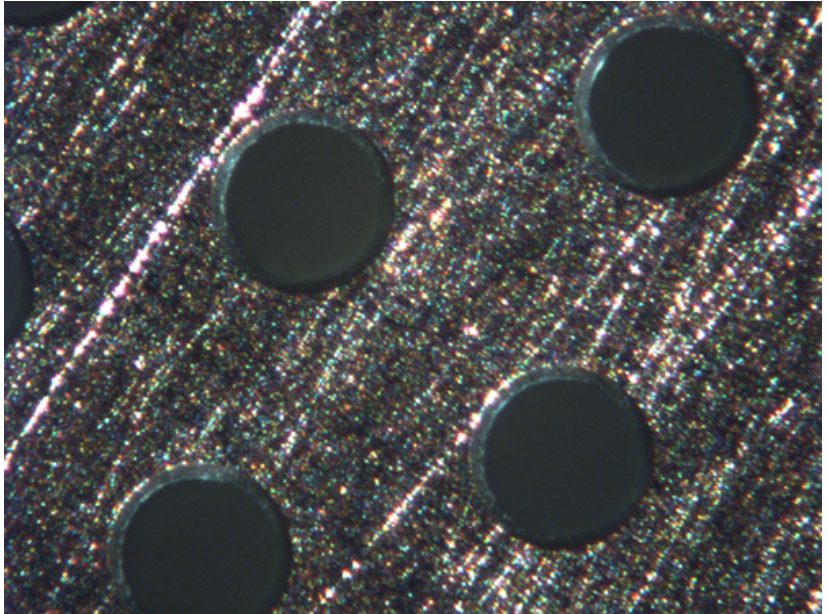
Plotted at 21:38:40 on 05/03/11 with Garfield version 7.23

Examples of Relevant LLNL TPC Hardware Electronics



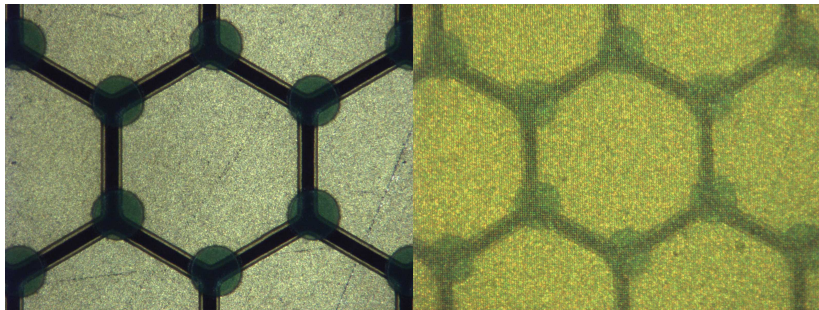
Examples of Relevant LLNL TPC Hardware

Micro-structure Gas Gain – LEM



Examples of Relevant LLNL TPC Hardware

Micro-structure Gas Gain –MICROMEAS



Some Suggestions the Next Steps for a Phenix TPC

- ▶ Develop a specifications and requirements document
- ▶ Identify key design decisions, study them, document each one
- ▶ Derive a basic WBS (from the the S&R doc and list of key design decisions) and from that a bottom up cost and schedule
- ▶ Identify risks, prioritize and develop studies/experiments to reduce risk
- ▶ Iterate

Some Key Design Decisions

- ▶ One or two volume
- ▶ Assembly: split or pull beam pipe through (also assemble in or out of IR)
- ▶ ID and OD, and eta coverage. Nail down allowable envelope, TPC and services.
- ▶ Pad geometry (rectangle, hex, chevron, etc..), size(as function of r), total number
- ▶ Gain uniformity requirement
- ▶ Acceptable ion feedback
- ▶ Aging: required total charge lifetime
- ▶ Gas mixture
- ▶ gas gain: wire, GEMs, LEMs, MICROMEGAS, combination.
- ▶ Acceptable field cage and end plate areal density
- ▶ Thermal requirements
- ▶ Field cage electric field uniformity requirement
- ▶ What calibrations are needed